COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

SEMICONDUCTOR PACKAGE WITH A HEAT SPREADER

the	specification of whic	ch .				
<u>X</u>	is attached hereto					
—	was filed on					
	as Application Serial No		and was amended on			
app app fore on v	cification, including to a cknowledge the lication in accordance I hereby claim fore lication(s) for paten	the claims, as amended to duty to disclose informate with Title 37, Code or eign priority benefits under the or inventor's certificatent or inventor's certificatent.	nd understand the content of by any amendment referred rmation which is material to of Federal Regulations, § 1. der Title 35, United States Co ate listed below and have ficate having a filing date be	ed to above. the patenta 56(a). Code, § 119 also identific	ability of this of any foreigned below any	
	Number	Country	Date Filed(yyyy/mm/dd)	Yes	No	
	92104001	Taiwan, R.O.C.	2003/2/26	X		
tran		the Patent and Tradem) and/or agent(s) to prosec ark Office connected therev	vith:		
	Belinda Lee Jiawei Huang Charles C.H. Wu	(Reg. No. 46,863 (Reg. No. 43,330 (Reg. No. 39,081))	(Reg. No.	53,226)	
	SEND CORRESPO	NDENCE TO:		DIRECT TELEPHONE CALLS TO: (Name and telephone number)		
-	JIANQ CHYUN Intellectual Property Office 7F1, No. 100, Roosevelt Rd., Sec. 2, Taipei 100, Taiwan, R.O.C. TEL: 886-2-2369 2800 FAX: 886-2-2369 7233			Belinda Lee		

COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature:

Sole or First Joint Inventor: Sung-Fei Wa

Sole of First Joint Inventor: Sung-Fei Wang

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